

REPLACEMENT CLAIMS

muc3 46. (Amended) An integrated circuit substrate comprising at least one buried conductor pattern provided within a monocrystalline substrate and surrounded by semiconductor material, said at least one buried conductor pattern having a spherical pattern, and a conductive path extending from said buried conductor pattern.

b1 47. (Amended) The integrated circuit of claim 46, further comprising a second buried conductor pattern having a pipe-shaped pattern.

c 48. (Amended) The integrated circuit of claim 46, further comprising a second buried conductor pattern having a plate-shaped pattern.

muc3 72. (New) An integrated circuit substrate comprising at least one buried conductor pattern provided within a monocrystalline substrate and surrounded by semiconductor material, said at least one buried conductor pattern having a plate-shaped pattern, and a conductive path extending from said buried conductor pattern.

b2 73. (New) The integrated circuit of claim 72, further comprising a second buried conductor pattern having a pipe-shaped pattern.

b2 74. (New) The integrated circuit of claim 73, further comprising a third buried conductor pattern having a spherical pattern.

b2 75. (New) An integrated circuit substrate comprising at least one buried conductor pattern provided within a monocrystalline substrate and surrounded by semiconductor material, said at least one buried conductor pattern having a pipe-shaped pattern, and a conductive path extending from said buried conductor pattern.

b2 76. (New) An integrated circuit substrate comprising at least two buried conductor patterns provided within a monocrystalline substrate and surrounded by semiconductor material, wherein a first of said at least two buried conductor patterns is

located below a second of said at least two buried conductor patterns and relative to a surface of said monocrystalline substrate, and a first conductive path extending from said first of said at least two buried conductor patterns and a second conductive path extending from said second of said at least two buried conductor patterns.

77. (New) The integrated circuit of claim 76, further comprising a third buried conductor pattern located below said at least two buried conductor patterns and relative to a surface of said monocrystalline substrate and a third conductive path extending from said third buried conductor pattern.

78. (New) The integrated circuit of claim 77, wherein said at least one of buried conductor patterns has a pipe-shaped pattern.

79. (New) The integrated circuit of claim 77, wherein said at least one of buried conductor patterns has a plate-shaped pattern.

80. (New) The integrated circuit of claim 77, wherein said at least one of buried conductor patterns has a spherical pattern.

81. (New) The integrated circuit of claim 77, wherein said conductive patterns are formed of a conductive material selected from the group consisting of copper, copper alloy, silver, silver alloy, gold, gold alloy, tungsten, tungsten alloy, aluminum and aluminum alloy.

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